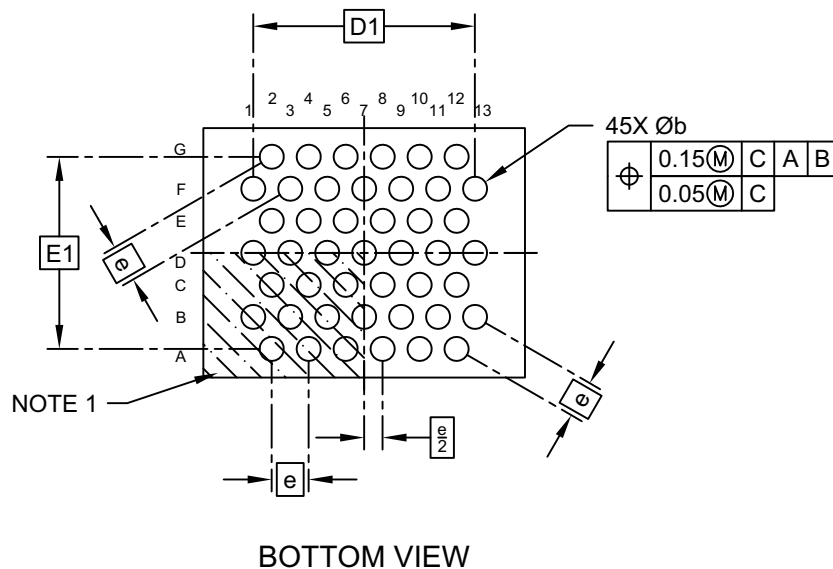
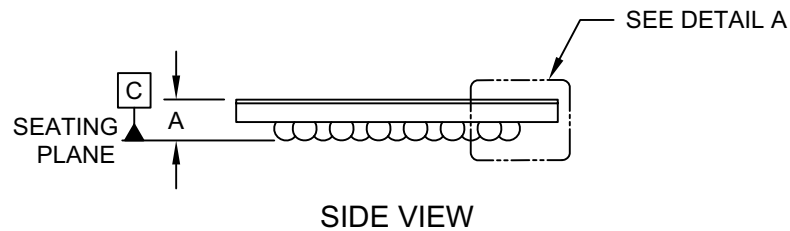
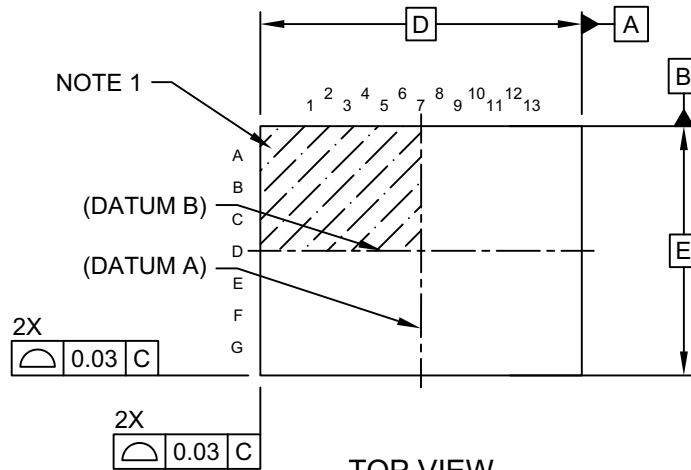


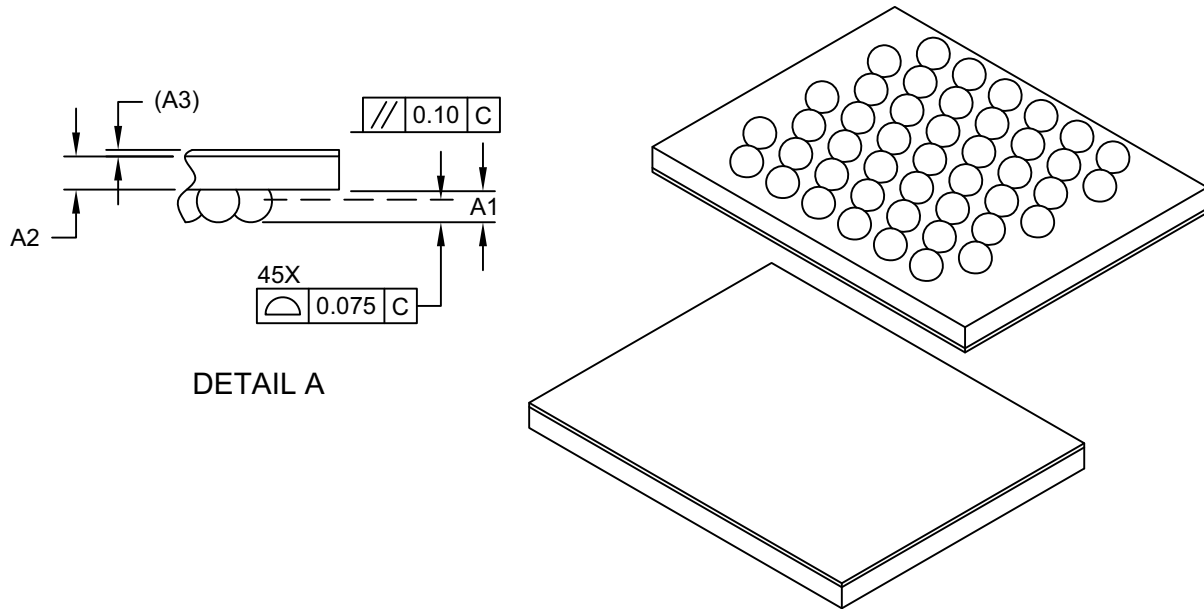
45-Ball Wafer Level Chip Scale Package (G2B) - 3.481x2.699 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



45-Ball Wafer Level Chip Scale Package (G2B) - 3.481x2.699 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



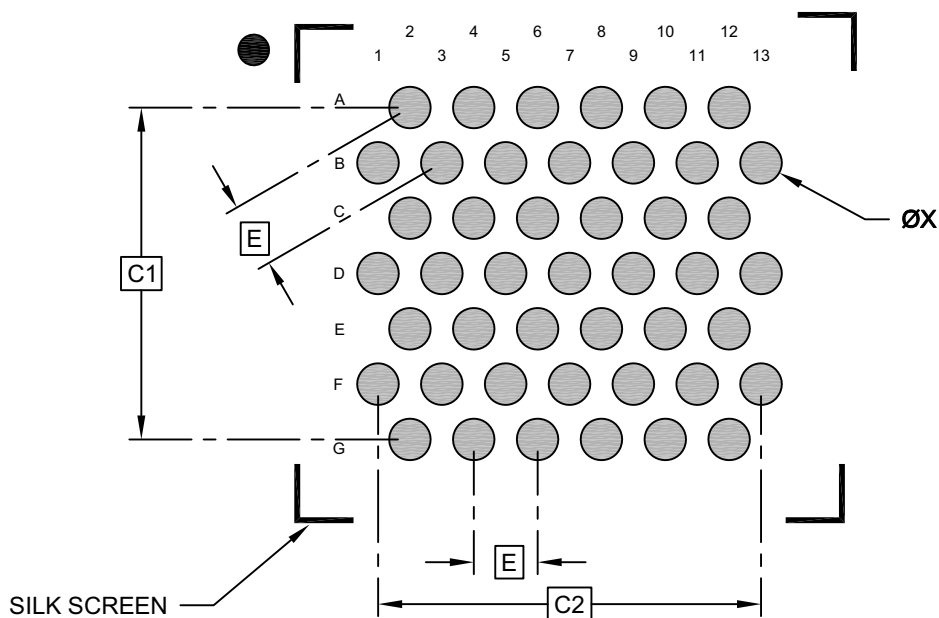
		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		45		
Pitch	e		0.40 BSC		
Overall Height	A	-	-	-	0.483
Bump Height	A1		0.17	0.20	0.23
Die Thickness	A2		0.178	0.203	0.228
Backside Coating	A3		0.04 REF		
Overall Length	D		3.481 BSC		
Overall Bump Pitch	D1		2.40 BSC		
Overall Width	E		2.699 BSC		
Overall Bump Pitch	E1		2.079 BSC		
Terminal Width	b		0.23	0.26	0.29

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

45-Ball Wafer Level Chip Scale Package (G2B) - 3.481x2.699 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1	2.079 BSC		
Contact Pad Spacing	C2	2.40 BSC		
Contact Pad Diameter (X45)	X		0.26	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.